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(12) **United States Design Patent**
Wei

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(54) **ELECTRONIC DEVICE ENCLOSURE**

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(**) **Term:** **14 Years**

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(51) **LOC (7) Cl.** **14-03**

(52) **U.S. Cl.** **D14/496**

(58) **Field of Search** D14/496, 133,
D14/135, 435, 454, 483; D21/324, 332;
273/148 B; 463/30-47; 206/308.1, 308.3,
307; 345/905

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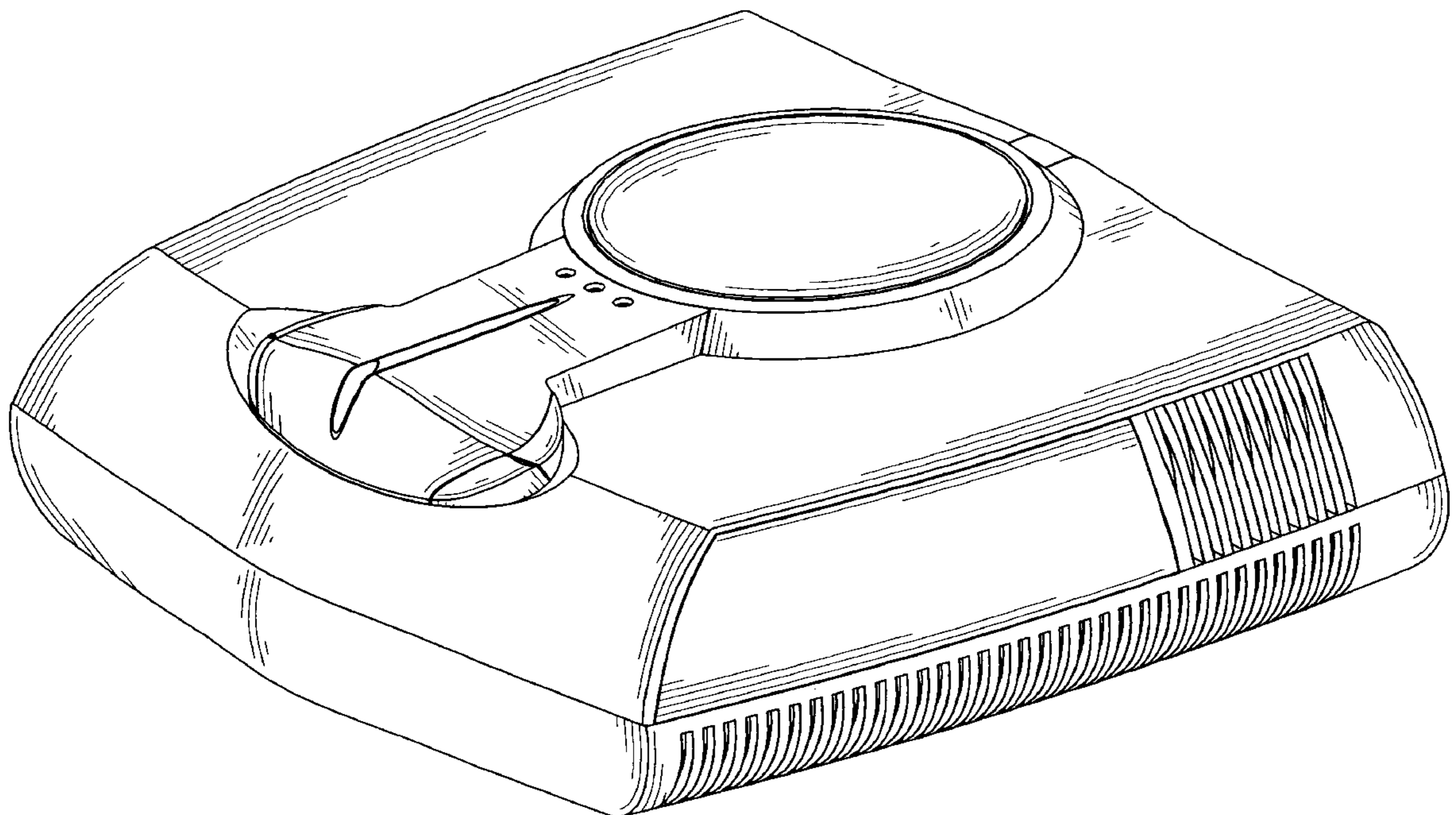
(57) **CLAIM**

The ornamental design for an electronic device enclosure, as shown.

DESCRIPTION

FIG. 1 is a perspective view of an electronic device enclosure of my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



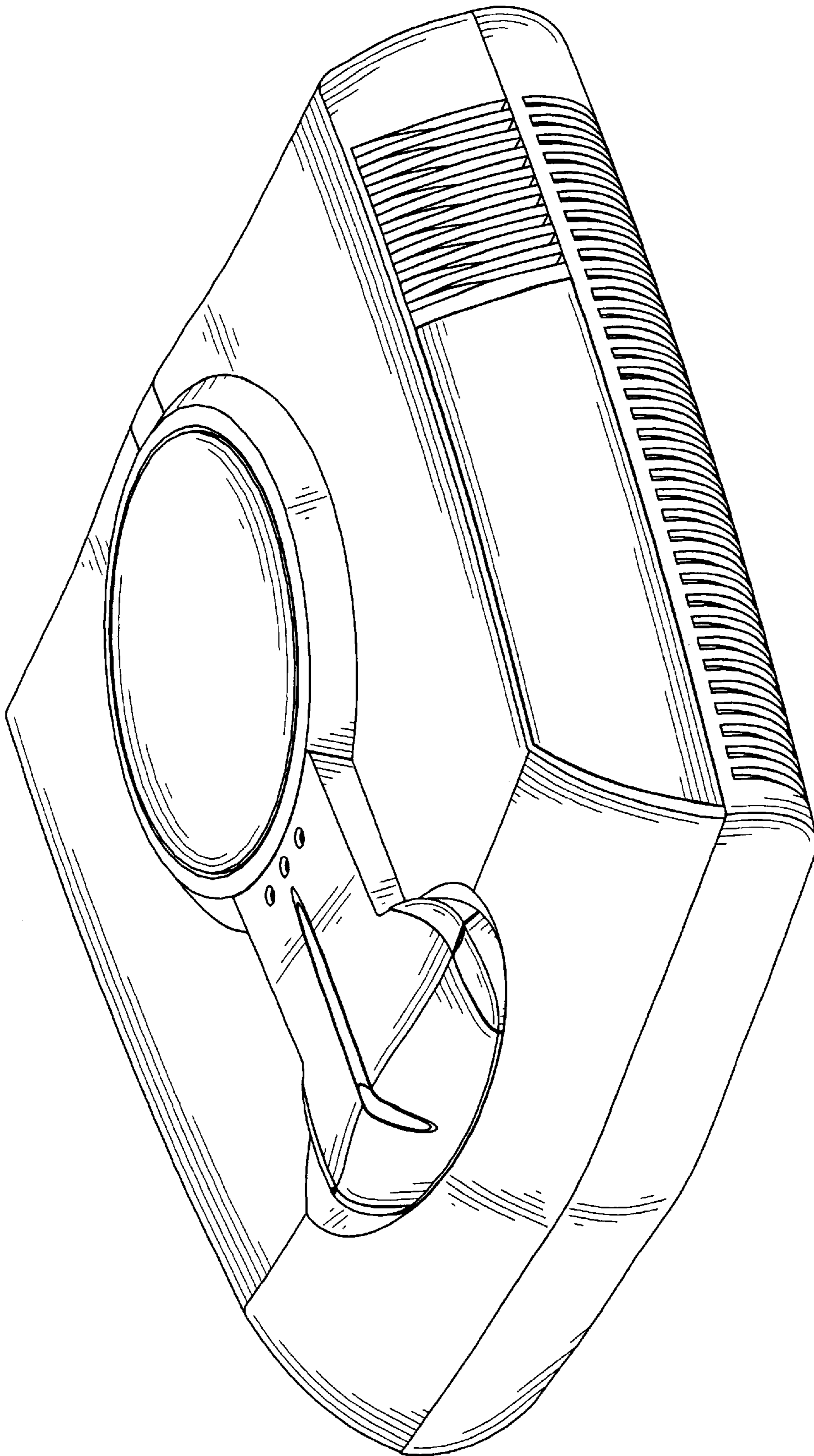


FIG. 1

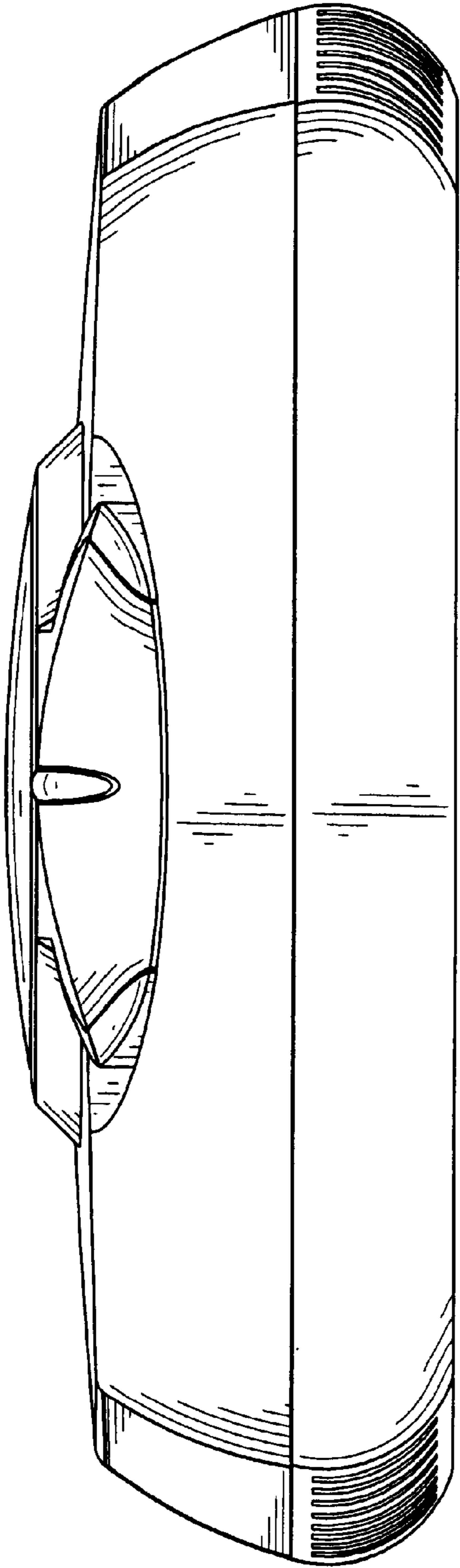


FIG. 2

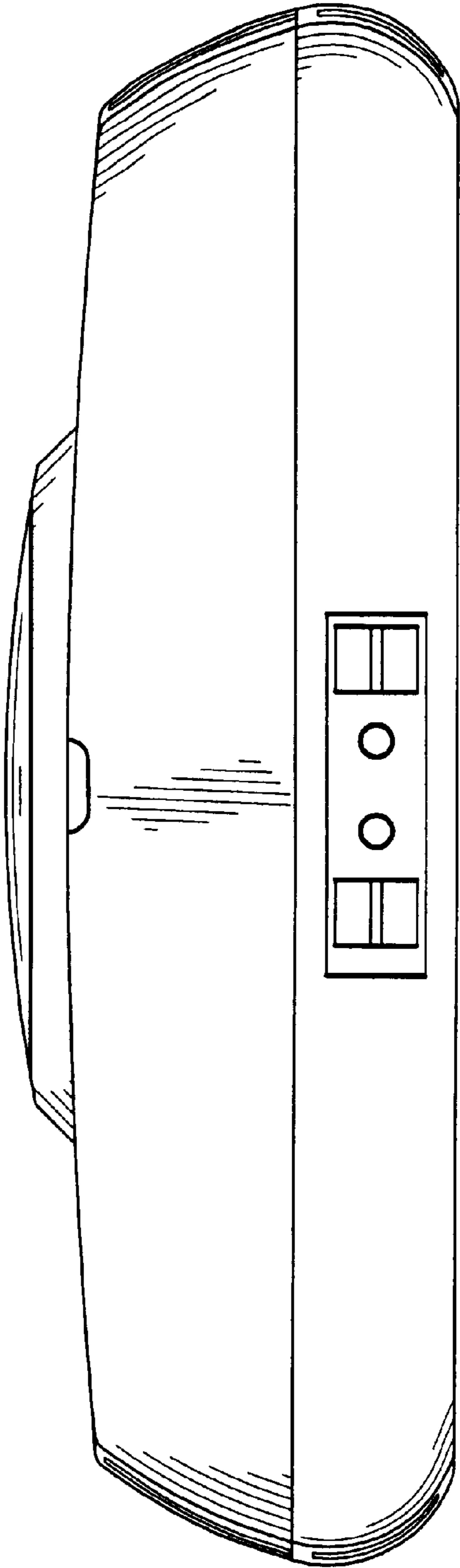


FIG. 3

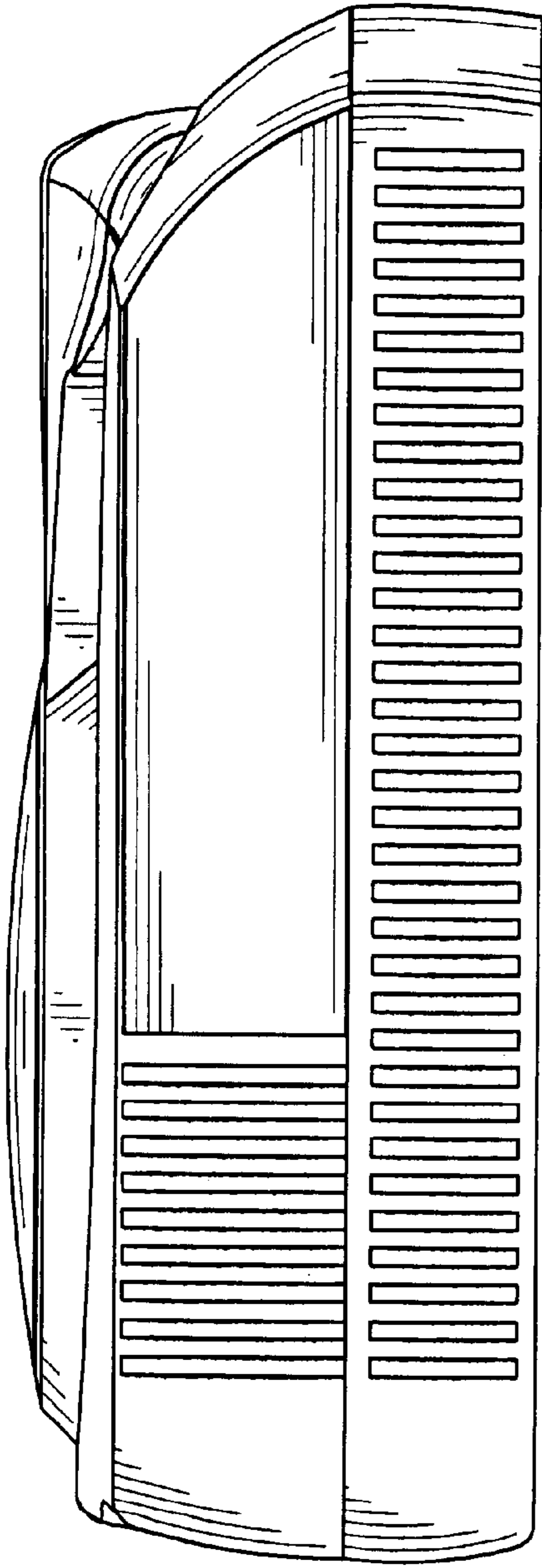


FIG. 4

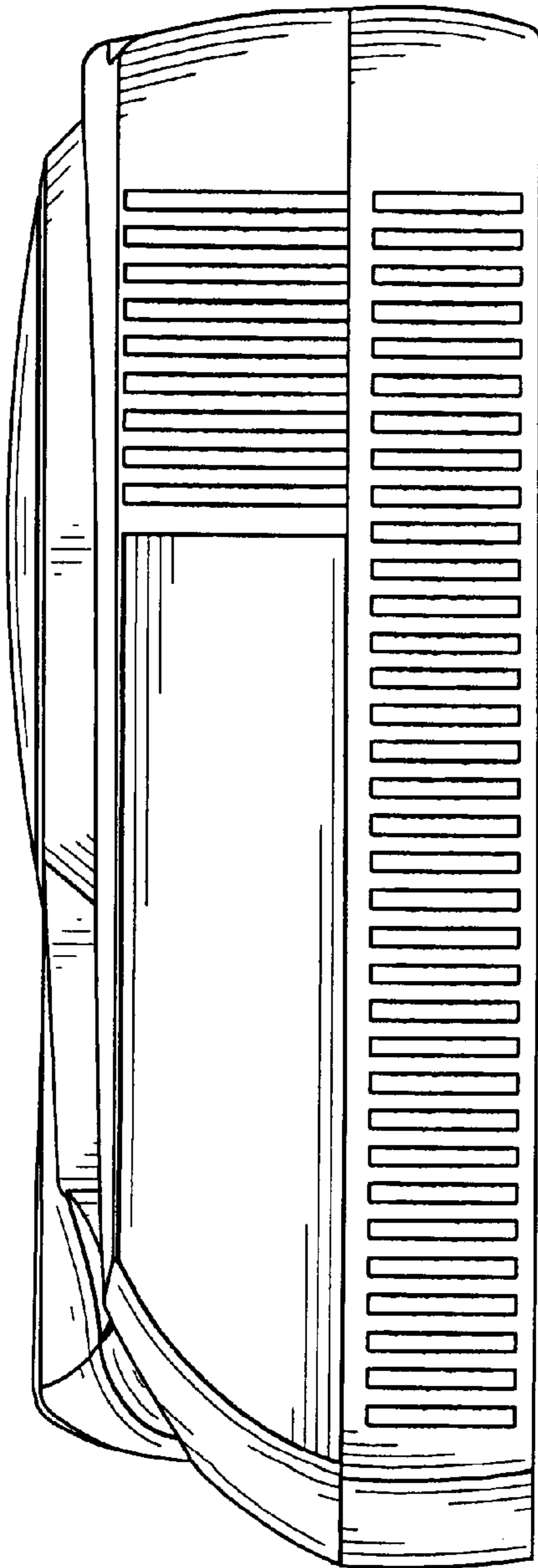


FIG. 5

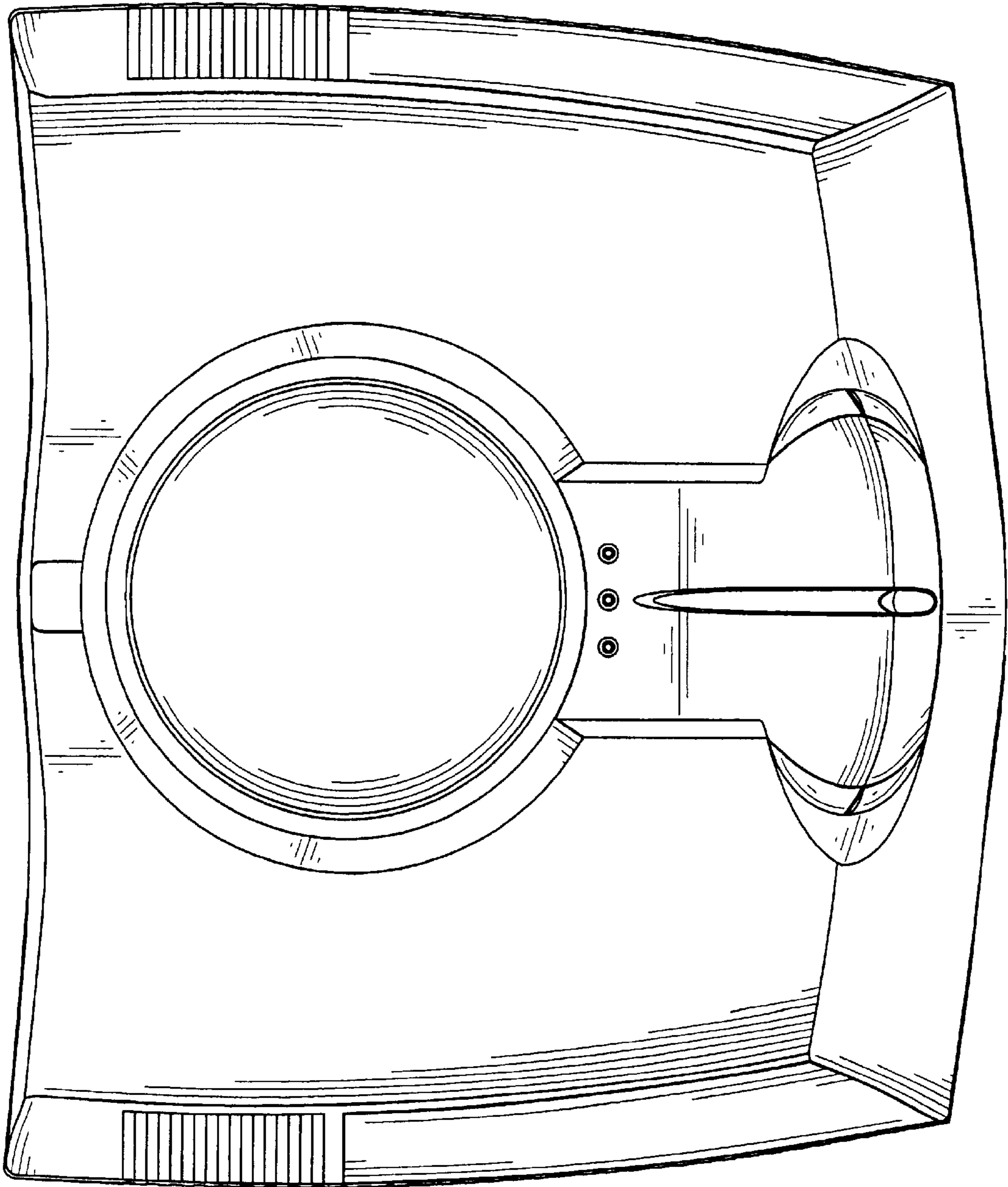


FIG. 6

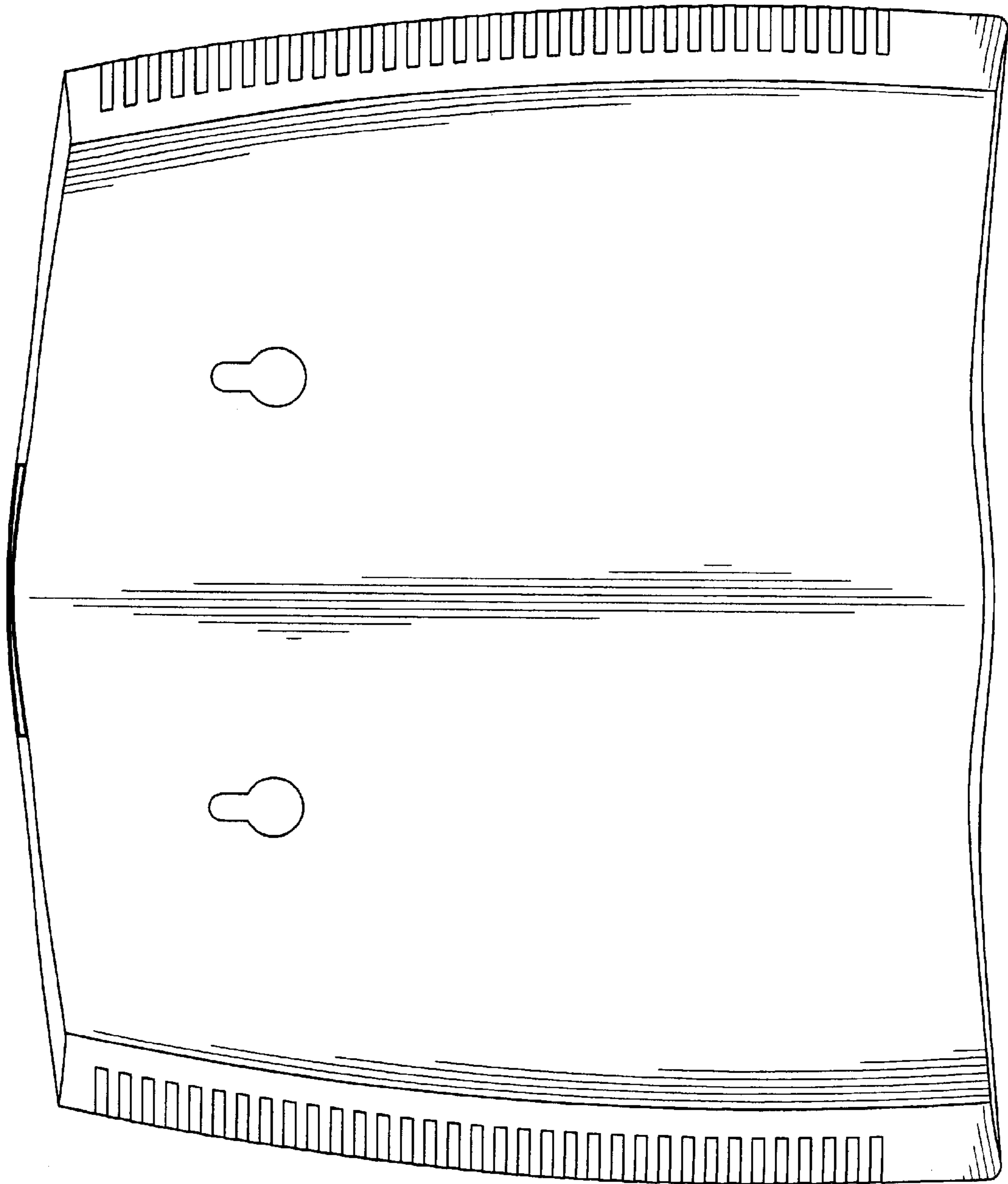


FIG. 7